



Patent Application No.: 10/763,306
Customer No.: 42717

IPW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Shih-Wei Chou, et al.	§	Docket No.:	TS01-1503 (24061.433)
Serial No.:	10/763,306	§	Examiner:	Colleen E. Rodgers
Filed:	January 23, 2004	§	Art Unit:	2813
For:	Method to Improve Planarity of Electroplated Copper	§	Conf. No.:	6528

RESPONSE TO SPECIES RESTRICTION

I. Introductory Comments

The present paper is being submitted in response to the Species Restriction - Office Action mailed August 4, 2005.

No fees, including extension of time fees, are believed necessary for consideration of the present paper. However, if any fees, including extension of time fees are necessary, the extension of time is hereby requested, and the Commissioner is hereby authorized to charge any fees, including those for the extension of time, to Haynes and Boone, LLP's Deposit Account No. 08-1394.

Election of Species is on page 2 of this paper.

Listing of Claims begins on page 3 of this paper.

Remarks/Arguments begin on page 9 of this paper.

II. Election

In the Office Action mailed August 4, 2005, the Examiner alleges that the application contains claims directed to the following species:

Species I: claims 4-24, wherein two baths in separate containers are disclosed

Species II: claims 25-39, wherein two baths in one container is disclosed

In response to the election of species requirement, Applicants elect Species I, corresponding to claims 4-24. Claims 1-3 is readable on the elected Species I, and is considered generic.